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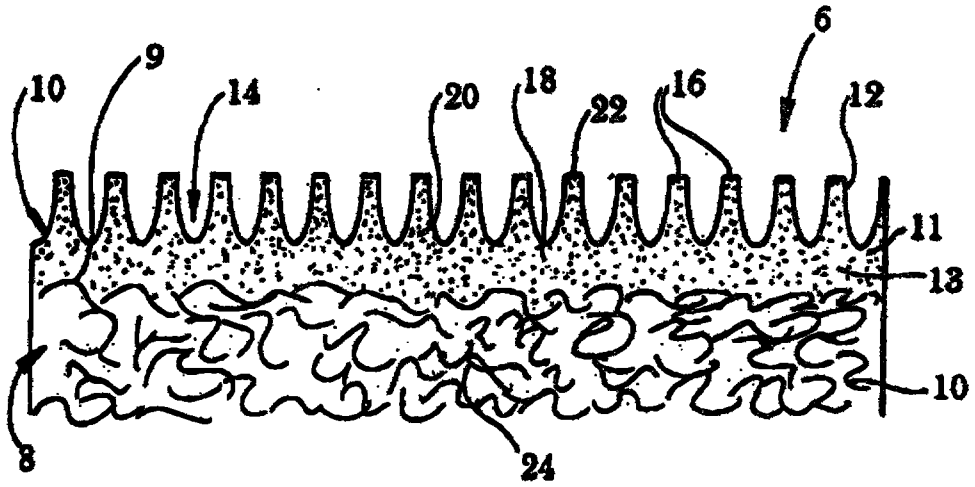
(54) Title: MANUFACTURING A MEMORY DISK OR SEMICONDUCTOR DEVICE USING AN ABRASIVE POLISHING SYSTEM, AND POLISHING PAD



(57) Abstract

Method of manufacturing a memory disk or a semiconductor device using a polishing apparatus (100) having a substrate and a fixed abrasive pad (6), the fixed abrasive pad (6) having a three–dimensional fixed abrasive polishing layer having a plurality of protrusions (16) and recesses (14) between the protrusions (16) and a plurality of nanoasperities, the abrasive polishing layer comprising a plurality of particles (18), the average particle size multiplied by the particle's valley abrasion number is less than 300, the polishing layer further comprising a polishing surface.